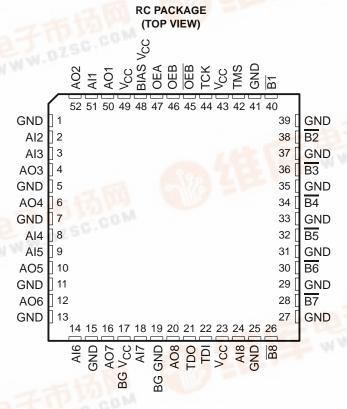
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- Compatible With IEEE Std 1194.1-1991 (BTL)
- TTL A Port, Backplane Transceiver Logic
  (BTL) B Port
- Open-Collector B-Port Outputs Sink 100 mA
- High-Impedance State During Power Up and Power Down
- BIAS V<sub>CC</sub> Pin Minimizes Signal Distortion During Live Insertion or Withdrawal
- B-Port Biasing Network Preconditions the Connector and PC Trace to the BTL High-Level Voltage



## description

The SN74FB2040 is an 8-bit transceiver designed to translate signals between TTL and backplane transceiver logic (BTL) environments.

The B port operates at BTL-signal levels. The open-collector B ports are specified to sink 100 mA. Two output enables (OEB and OEB) are provided for the B outputs. When OEB is high and OEB is low, the B port is active and reflects the inverse of the data present at the A-input pins. When OEB is low, OEB is high, or V<sub>CC</sub> is less than 2.1 V, the B port is turned off.

The A port operates at  $\overline{TL}$ -signal levels and has separate input and output pins. The A outputs reflect the inverse of the data at the  $\overline{B}$  port when the A-port output enable (OEA) is high. When OEA is low or when  $V_{CC}$  is less than 2.1 V, the A outputs are in the high-impedance state.

The pins TMS, TCK, TDI, and TDO are nonfunctional, i.e., not intended for use with the IEEE Std 1149.1 (JTAG) test bus. TMS and TCK are not connected, and TDI is shorted to TDO.

BIAS V<sub>CC</sub> establishes a voltage between 1.62 V and 2.1 V on the BTL outputs when V<sub>CC</sub> is not connected.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### **ORDERING INFORMATION**

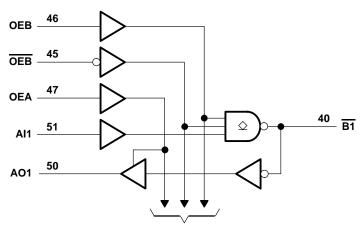
TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	QFP – RC	Tube	SN74FB2040RC	FB2040	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

	INPUTS		FUNCTION			
OEB	OEB	OEA	FUNCTION			
L	Х	L	Isolation			
Χ	Н	L				
L	Х	Н	D data to AO hus			
Х	Н	Н	B data to AO bus			
Н	L	L	Al data to B bus			
Н	L	Н	$\overline{AI}$ data to B bus, $\overline{B}$ data to AO bus			

# functional block diagram



**To Seven Other Channels** 



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$-0.5$ V to 7 V
Input voltage range, V <sub>I</sub> : Except B port	$-1.2 \text{ V to 7 V}$
B port	$-1.2\;V$ to 3.5 $V$
Voltage range applied to any $\overline{B}$ output in the disabled or power-off state, $V_O$	
Voltage range applied to any output in the high state, V <sub>O</sub> : A port	$\dots$ -0.5 V to V <sub>CC</sub>
Input clamp current, I <sub>IK</sub> : Except B port	–40 mA
B port	–18 mA
Current applied to any single output in the low state, IO: A port	48 mA
$\overline{B}$ port	
Package thermal impedance, θ <sub>JA</sub> (see Note 1)	44°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

# recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V <sub>CC</sub> , BIAS V <sub>CC</sub> , BG V <sub>CC</sub>	Supply voltage		4.5	5	5.5	V
\/	High-level input voltage	B port	1.62		2.3	V
VIH	nigri-iever iriput voitage	2			7 °	
\/	Low-level input voltage    B port		0.75		1.47	V
VIL					0.8	V
lik	Input clamp current				-18	mA
loн	High-level output current	AO port			-3	mA
la.	Low-level output current  AO port  B port				24	A
lOL					100	mA
TA	Operating free-air temperature		0		70	°C

NOTE 2: To ensure proper device operation, all unused inputs must be terminated as follows: A and control inputs to V<sub>CC</sub>(5 V) or GND, and B inputs to GND only. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# SN74FB2040 8-BIT TTL/BTL TRANSCEIVER

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	TEST CONDITIONS				
Vive	B port	$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2	V
VIK	Except B port	$V_{CC} = 4.5 \text{ V},$	$I_I = -40 \text{ mA}$			-0.5	V
Vон	AO port	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5	3.3		V
	AO port	$V_{CC} = 4.5 \text{ V},$	I <sub>OL</sub> = 24 mA		0.35	0.5	
VOL	5	V <sub>CC</sub> = 4.5 V	$I_{OL} = 80 \text{ mA}$	0.75		1.1	V
	B port	VCC = 4.5 V	$I_{OL} = 100 \text{ mA}$				
II	Except B port	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			50	μΑ
I <sub>IH</sub> ‡	Except B port	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			50	μΑ
. +	Except B port	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			-50	
111_‡	B port	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.75 V		-	-100	μΑ
ІОН	B port	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	V <sub>O</sub> = 2.1 V			100	μΑ
lozh	AO port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			50	μΑ
lozL	AO port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0.5 V			-50	μΑ
lozpu	A port	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$	V <sub>O</sub> = 0.5 V to 2.7 V			50	μΑ
lozpd	A port	$V_{CC} = 2.1 \text{ V to } 0,$	V <sub>O</sub> = 0.5 V to 2.7 V			-50	μΑ
IOS§	AO port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0	-30		-180	mA

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

	PARAMETER	TEST CONDITIONS	MIN TYP† MAX	UNIT
	Al port to B port	Vac EEV la 0	40	A
ICC	B port to AO port	$V_{CC} = 5.5 \text{ V}, \qquad I_{O} = 0$	70	mA
Ci	Al port	VI = VCC or GND	3.5	pF
G	Control inputs	AL = ACC OLGIND	3	] Pr
Co	AO port	$V_O = V_{CC}$ or GND	6	pF
C <sub>io</sub>		V <sub>CC</sub> = 0 to 4.5 V	5	pF
	B port per IEEE Std 1194.1-1991	V <sub>CC</sub> = 4.5 V to 5.5 V	5	] Pi

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

## live-insertion specifications over recommended operating free-air temperature range

P/	RAMETER		MIN	MAX	UNIT		
ICC (BIAS VCC)		$V_{CC} = 0 \text{ to } 4.5 \text{ V},$	$V_B = 0 \text{ to } 2 \text{ V},$	$V_I$ (BIAS $V_{CC}$ ) = 4.5 V to 5.5 V		450	
ICC (E	SIAS ACC)	$V_{CC} = 4.5 \text{ to } 5.5 \text{ V},$	$V_B = 0$ to 2 V,	$V_I$ (BIAS $V_{CC}$ ) = 4.5 V to 5.5 V		10	μΑ
٧o	B port	$V_{CC} = 0$ ,	$V_{I}$ (BIAS $V_{CC}$ ) = 5 $V$		1.62	2.1	٧
		$V_{CC} = 0$ ,	$V_{B} = 1 V,$	$V_I$ (BIAS $V_{CC}$ ) = 4.5 V to 5.5 V	-1		
ΙO	B port	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	OEB = 0 to 0.8 V			100	μΑ
		$V_{CC} = 0 \text{ to } 2.2 \text{ V},$	OEB = 0 to 5 V			100	



<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C. ‡ For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

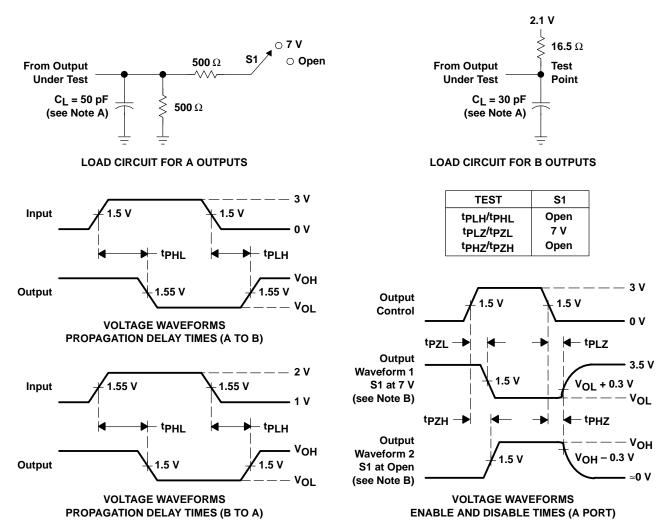
# SN74FB2040 8-BIT TTL/BTL TRANSCEIVER

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# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	۷ <sub>0</sub>	CC = 5 V A = 25°C	', ;	MIN	MAX	UNIT
	(INFOT)	(001701)	MIN	TYP	MAX			
<sup>t</sup> PLH	Al	IВ	3.2	4.5	6	2.4	6.5	ns
t <sub>PHL</sub>	Al	В	2.8	4.2	5.6	2.7	5.8	115
tPLH	B	AO	2.3	3.8	5.7	1.9	6.2	ns
tpHL	В	AO	2.3	4.2	5.9	2	8.2	115
tPLH	OEB	B	3.7	5.1	6.7	3	7	20
tpHL	UEB	В	3.1	4.6	5.9	3	6.1	ns
tPLH	<del>050</del>	B	3.6	5.2	6.8	3.3	7	ns
t <sub>PHL</sub>	OEB	В	2.9	4.4	5.9	2.6	6.1	115
<sup>t</sup> PZH	OEA	AO	2.5	4	5.5	2.1	5.8	20
tpZL	OEA	AO	2.1	3.6	4.8	2	5	ns
t <sub>PHZ</sub>	OEA	AO	2.3	4.1	5.9	1.9	6.5	20
tPLZ	OEA	AO	1.6	3.1 4.5	4.5	1.4	4.7	ns
t <sub>sk(p)</sub>	Skew for any single channel  tp	HL - tPLH , AI to B or B to AO		0.5				ns
t <sub>sk(o)</sub>	Skew between drivers in the same package, Al to B or B to AO			0.4				ns
t <sub>r</sub>	Rise time, 1.3 V to 1.8 V, $\overline{B}$ port			2.8	3.8	1.7		ns
t <sub>f</sub>	Fall time, 1.8 V to 1.3 V, B port			1.9	3	1	4.2	ns
t <sub>(pr)</sub>	B-port input pulse rejection					1	3.4	ns

#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: TTL inputs: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
  - D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





#### PACKAGE OPTION ADDENDUM

6-Dec-2006

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74FB2040RC	ACTIVE	QFP	RC	52	96	TBD	CU SNPB	Level-2-240C-1YR
SN74FB2040RCG3	ACTIVE	QFP	RC	52	96	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
SN74FB2040RCR	ACTIVE	QFP	RC	52	500	TBD	CU SNPB	Level-2-240C-1YR
SN74FB2040RCRG3	ACTIVE	QFP	RC	52	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

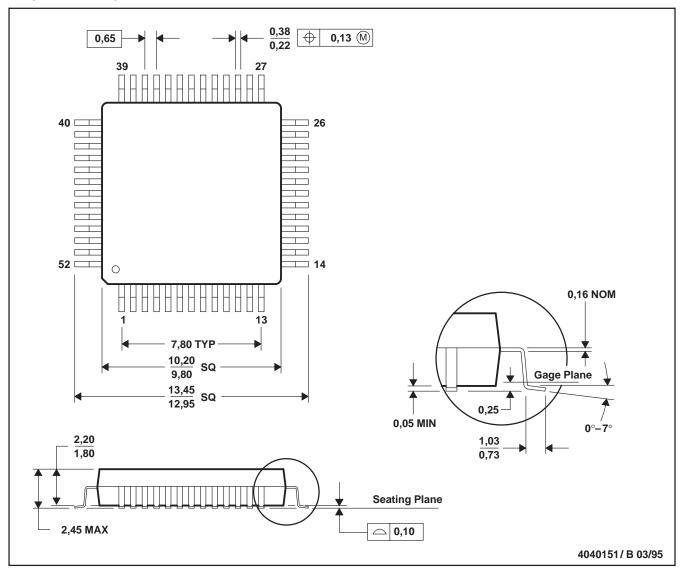
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## RC (S-PQFP-G52)

#### PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-022

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